

Amendments to the Claims

This listing of the Claims will replace all prior versions and listings of the claims in this patent application.

Listing of the Claims

Claims 1-43 (canceled)

44. (currently amended) A chip package comprising:

a substrate;

a semiconductor chip over said substrate;

an identity of product and manufacturer or a bar code on a back surface of said semiconductor chip;

multiple metal bumps on between a front surface of said semiconductor chip and said substrate, wherein said front surface is an active device surface of said semiconductor chip;
and

an optically transparent layer a protecting structure over said back surface, wherein said optically transparent layer covers said identity of product and manufacturer or semiconductor chipsaid bar code, and said substrate, wherein said identity of product and manufacturer or said semiconductor chip bar code is visible through said optically transparent layer. protecting structure.

Claims 45-47 (canceled)

48. (currently amended) The chip package of claim 44 further comprising a substrate and an underfill material between said semiconductor chip-front surface and a top surface of said substrate, and wherein said underfill encloses said multiple bumps.

49. (currently amended) The chip package of claim 48 47 further comprising multiple balls under a bottom surface of said substrate.

Claims 50-52 (canceled)

53. (new) The chip package of claim 44, wherein said optically transparent layer is non-black.

54. (new) The chip package of claim 44, wherein said optically transparent layer comprises a colored material.

55. (new) The chip package of claim 44, wherein said optically transparent layer comprises a material colored with additives.

56. (new) The chip package of claim 44, wherein said optically transparent layer comprises a molding material.

57. (new) The chip package of claim 44, wherein said optically transparent layer comprises a glob top material.

58. (new) The chip package of claim 44, wherein said optically transparent layer comprises epoxy.

59. (new) The chip package of claim 44, wherein said bar code is readable by a code reader device through said optically transparent layer.

60. (new) The chip package of claim 44, wherein said metal bump comprises solder.